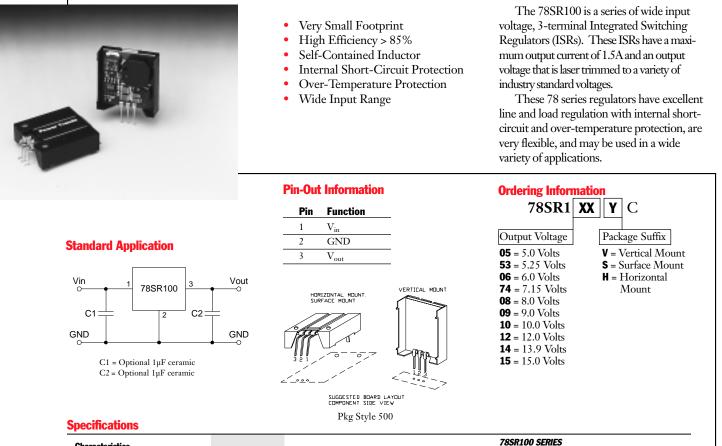
For assistance or to order; call (800) 531-5782

# 78SR100 Series

#### 1.5 AMP POSITIVE STEP-DOWN INTEGRATED SWITCHING REGULATOR

### **Revised 6/30/98**



Characteristics			78SR10				
(T <sub>a</sub> = 25°C unless noted)	Symbols	Conditions	Min	Тур	Max	Units	
Output Current	Io	Over V <sub>in</sub> range	0.1*	_	1.5	Α	
Short Circuit Current	I <sub>sc</sub>	$V_{in} = V_{in} \min$		3.5		Apk	
Input Voltage Range	$V_{in}$	$0.1 \le I_o \le 1.5A$ $V_o = 5V$ $V_o = 12V$	7 14.5	_	30 30	V V	
Output Voltage Tolerance	$\Delta V_{o}$	Over $V_{in}$ range, $I_o=1.5A$ $T_a = 0^{\circ}C$ to +60°C	—	±1.0	±2.0	%V <sub>o</sub>	
Line Regulation	Reg <sub>line</sub>	Over V <sub>in</sub> range	_	±0.2	±0.4	%Vo	
Load Regulation	Reg <sub>load</sub>	$0.1 \le I_o \le 1.5 A$	_	±0.1	±0.2	%Vo	
V <sub>o</sub> Ripple/Noise	$V_n$	$V_{in} = 9V, I_o = 1.5A$ $V_o = 5V$ $V_{in} = 16V, I_o = 1.5A$ $V_o = 12V$	—	50 80	—	mV <sub>pp</sub> mV <sub>pp</sub>	
Transient Response	t <sub>tr</sub>	50% load change $V_0$ over/undershoot	_	100 30	_	μSec %Vo	
Efficiency	η	$\begin{array}{llllllllllllllllllllllllllllllllllll$	_	85 90	_	% %	
Switching Frequency	$f_{ m o}$	Over V <sub>in</sub> range, I <sub>o</sub> =1.5A	600	650	700	kHz	
Absolute Maximum Operating Temperature Range	T <sub>a</sub>	-	-40	-	+85	°C	
Recommended Operating Temperature Range	Та	Free Air Convection, (40-60LFM) At V <sub>in</sub> = 24V, I <sub>o</sub> =1.0A	-40	_	+80**	°C	
Thermal Resistance	$\theta_{ja}$	Free Air Convection, (40-60LFM)		45	_	°C/W	
Storage Temperature	T <sub>s</sub>	_	-40	_	+125	°C	
Mechanical Shock	—	Per Mil-STD-883D, Method 2002.3	_	500	_	G's	
Mechanical Vibration	—	Per Mil-STD-883D, Method 2007.2, 20-2000 Hz, soldered in a PC board	_	5	_	G's	
Weight	_	_		6.5	_	grams	

\*ISR will operate down to no load with reduced specifications.

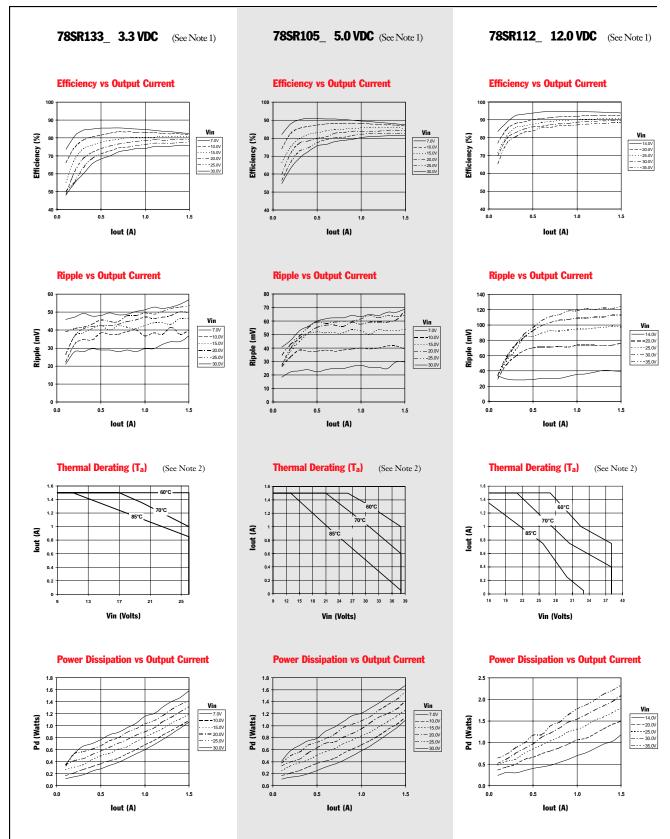
\*\*See Thermal Derating chart.

e s

78SR100

**CHARACTERISTIC** 

## DATA



Note 1: All data listed in the above graphs, except for derating data, has been developed from actual products tested at 25°C. This data is considered typical data for the ISR. Note 2: Thermal derating graphs are developed in free air convection cooling of 40-60 LFM. (See Thermal Application Notes.)



2-Feb-2014

## PACKAGING INFORMATION

Orderable Device	Status	Package Type	Package	Pins	Package	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking	Samples
	(1)		Drawing		Qty	(2)	(6)	(3)		(4/5)	
78SR105SCT	OBSOLETE	SIP MODULE	EFC	3		TBD	Call TI	Call TI	-40 to 85		
78SR106SCT	OBSOLETE	SIP MODULE	EFC	3		TBD	Call TI	Call TI	-40 to 85		
78SR108SCT	OBSOLETE	SIP MODULE	EFC	3		TBD	Call TI	Call TI	-40 to 85		
78SR109SC	OBSOLETE	SIP MODULE	EFC	3		TBD	Call TI	Call TI	-40 to 85		
78SR109SCT	OBSOLETE	SIP MODULE	EFC	3		TBD	Call TI	Call TI	-40 to 85		
78SR110SC	OBSOLETE	SIP MODULE	EFC	3		TBD	Call TI	Call TI	-40 to 85		
78SR110SCT	OBSOLETE	SIP MODULE	EFC	3		TBD	Call TI	Call TI	-40 to 85		
78SR110VC	OBSOLETE	SIP MODULE	EFD	3		TBD	Call TI	Call TI	-40 to 85		
78SR112SCT	OBSOLETE	SIP MODULE	EFC	3		TBD	Call TI	Call TI	-40 to 85		
78SR114SC	OBSOLETE	SIP MODULE	EFC	3		TBD	Call TI	Call TI	-40 to 85		
78SR114SCT	OBSOLETE	SIP MODULE	EFC	3		TBD	Call TI	Call TI	-40 to 85		
78SR114WC	OBSOLETE	SIP MODULE	EFW	3		TBD	Call TI	Call TI	-40 to 85		
78SR115SC	OBSOLETE	SIP MODULE	EFC	3		TBD	Call TI	Call TI	-40 to 85		
78SR115SCT	OBSOLETE	SIP MODULE	EFC	3		TBD	Call TI	Call TI	-40 to 85		
78SR153SCT	OBSOLETE	SIP MODULE	EFC	3		TBD	Call TI	Call TI	-40 to 85		
78SR153TC	OBSOLETE	SIP MODULE	EFT	3		TBD	Call TI	Call TI	-40 to 85		
78SR174SCT	OBSOLETE	SIP MODULE	EFC	3		TBD	Call TI	Call TI	-40 to 85		

<sup>(1)</sup> The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW**: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)



2-Feb-2014

<sup>(3)</sup> MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

<sup>(4)</sup> There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

<sup>(5)</sup> Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

<sup>(6)</sup> Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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